Final Product Change Notification

201407012F01

Issue Date: 27-Nov-2014
Effective Date: 07-Mar-2015

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Change Category

[ ] Wafer Fab process
[ ] Wafer Fab materials
[ ] Wafer Fab location
[ ] Assembly Process
[X] Assembly Materials
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[ ] Product Marking
[X] Electrical spec./Test coverage
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Change of bond wire and release of 2nd source mold compound in DFN2020-3 (SOT1061)

Details of this Change

Scheduled changes affect low VCEsat ("BISS") transistors in DFN2020-3 (SOT1061) package only.

(1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.
(2) A second source mold compound supplier will be introduced.
(3) In the datasheet of PBSS4330PA and PBSS5330PA, the measurement condition of ICES will be changed from VCE=30V to VCE=24V.

Old product: Wire material is Au, (with currently used mold compound suppliers)
Changed product: Wire material is Cu or Au (with currently used first and new second source mold compound supplier)

The design and materials of all other components will remain unchanged: die, die attach, and lead frame.

Reliability qualification and full electrical characterization over temperature have been performed. For details please see the Self Qualification Report.
No change on thermal behavior or mechanical dimensions. Electrical parameters (apart from the mentioned change of the ICES measurement condition) will remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
(2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM for associated types in DFN2020-3 (SOT1061) package. The second source supplier is already well established for NXP semiconductor products.
(3) The measurement condition is adapated to the standard condition used for NXP BISS transistors.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 23-Dec-2014.

Production

Planned first shipment 01-Apr-2015

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 27-Dec-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	GA Customer Support
e-mail address	DiscrQA.Helpdesk.GA-Products@nxp.com

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